

## 100V N-Channel Power MOSFET

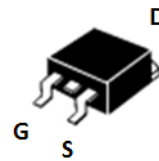
### DESCRIPTION :

- Super high dense cell design for extremely low  $R_{DS(ON)}$
- High power and current handing capability
- $R_{DS(ON),max.}=3.0m\Omega@V_{GS}=10V$
- RoHS compliant

$V_{DS}$	100V
$I_D$	209A
$R_{DS(ON),MAX} @V_{GS}=10V$	3m $\Omega$

### TYPICAL APPLICATIONS :

- Synchronous Rectification
- Power Management
- Load Switch



TO-263

### MAXIMUM RATINGS (at $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	$I_D$	209 132	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	836	A
Power dissipation	$T_C=25^\circ\text{C}$ Derate above 25 C	$P_D$	236 1.89	W W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy	$L = 10\text{mH}$ , $I_{AS} = 41\text{A}$ , $V_{DD} = 24\text{V}$ , $R_G = 25\Omega$ , Starting $T_J = 25\text{ }^\circ\text{C}$	$E_{AS}$	840	mJ
Single Pulsed Avalanche Current	$L = 10\text{mH}$ , $I_{AS} = 41\text{A}$ , $V_{DD} = 24\text{V}$ , $R_G = 25\Omega$ , Starting $T_J = 25\text{ }^\circ\text{C}$	$I_{AS}$	41	A
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

Notes : 1. Repetitive rating; pulse width limited by maximum junction temperature.

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction – Ambient Junction - Case	$R_{\theta(jA)}$ $R_{\theta(jC)}$	62.5 0.53	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS (at  $T_c = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage $V_{GS} = 0V, I_D = 250\mu A$	$BV_{DSS}$	100			V
Zero Gate Voltage Drain Current $V_{DS} = 100V, V_{GS} = 0V$	$I_{DSS}$			1	$\mu A$
Gate-Source Leakage Current $V_{GS} = \pm 20V, V_{DS} = 0V$	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage $V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(th)}$	2.0		4.0	V
Drain-Source On-State Resistance $V_{GS} = 10V, I_D = 20A$	$R_{DS(on)}$		2.5	3.0	m $\Omega$
Input capacitance $f=1MHz, V_{DS}=50V, V_{GS}=0V$	$C_{iss}$		6710		pF
Output capacitance $f=1MHz, V_{DS}=50V, V_{GS}=0V$	$C_{oss}$		1580		pF
Reverse transfer capacitance $f=1MHz, V_{DS}=50V, V_{GS}=0V$	$C_{rss}$		45		pF
Total Gate Charge $V_{DD}=50V, I_D=20A, V_{GS}=10V$	$Q_G$		90		nC
Gate to Source Charge $V_{DD}=50V, I_D=20A, V_{GS}=10V$	$Q_{GS}$		22		nC
Gate to Drain Charge $V_{DD}=50V, I_D=20A, V_{GS}=10V$	$Q_{GD}$		22		nC
Turn-on delay time $V_{DD}=50V, V_{GS}=10V, I_D=20A, R_{GEN}=5\Omega$	$t_{d(ON)}$		39		ns
Turn-on Rise time $V_{DD}=50V, V_{GS}=10V, I_D=20A, R_{GEN}=5\Omega$	$t_r$		20		ns
Turn-off delay time $V_{DD}=50V, V_{GS}=10V, I_D=20A, R_{GEN}=5\Omega$	$t_{d(OFF)}$		69		ns
Turn-off Fall time $V_{DD}=50V, V_{GS}=10V, I_D=20A, R_{GEN}=5\Omega$	$t_f$		32		ns

## Body Diode

Drain to Source Diode Forward Current	$I_S$			196	A
Drain to Source Diode Forward Voltage <sup>(2)</sup> $V_{GS} = 0V, I_S = 1.0A$	$V_{SD}$			1.2	V
Reverse Recovery Time $I_F = 20A, di/dt = 100A/\mu s$	$T_{RR}$		107		Ns
Reverse Recovery Charge $I_F = 20A, di/dt = 100A/\mu s$	$Q_{RR}$		192		nC

Note 2: Pulse Test : Pulse Width < 300 $\mu s$ , Duty Cycle < 2%.

Typical Characteristics

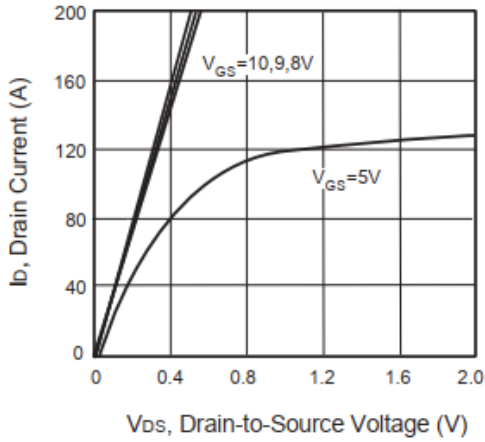


Figure 1. Output Characteristics

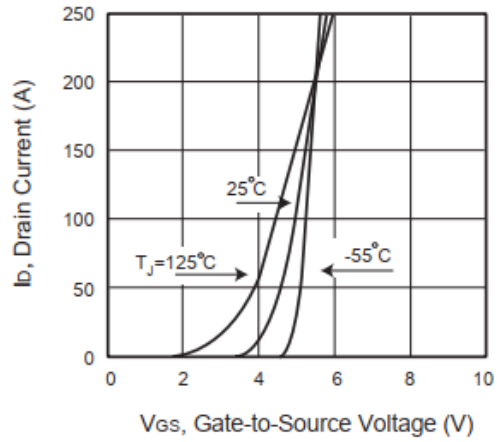


Figure 2. Transfer Characteristics

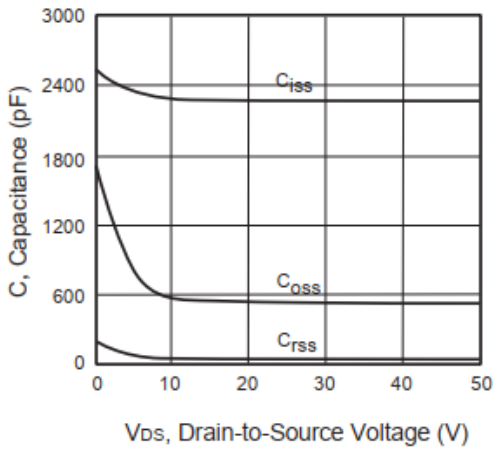


Figure 3. Capacitance

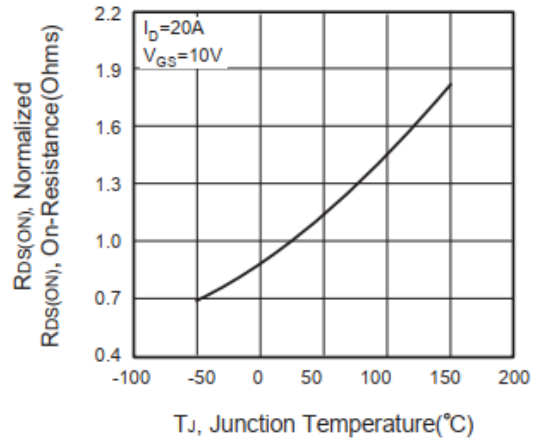


Figure 4. On-Resistance Variation with Temperature

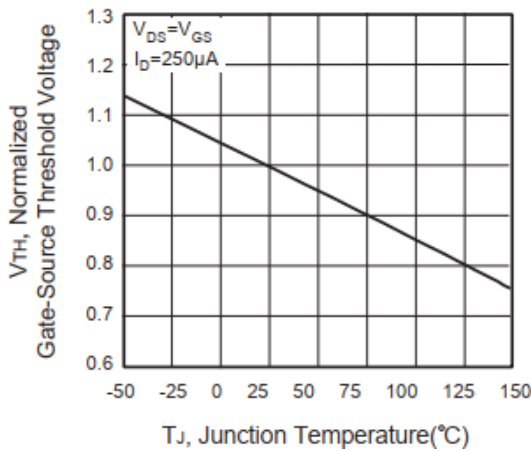


Figure 5. Gate Threshold Variation with Temperature

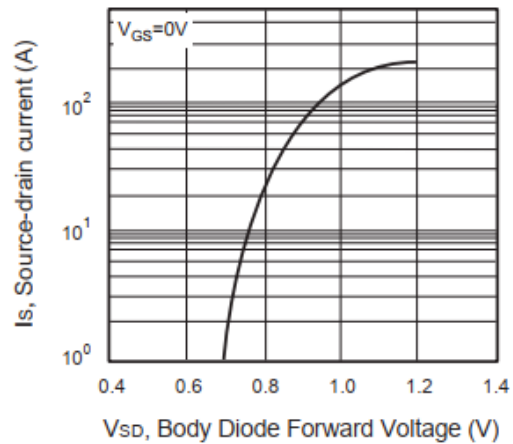


Figure 6. . Body Diode Forward Voltage Variation with Source Current

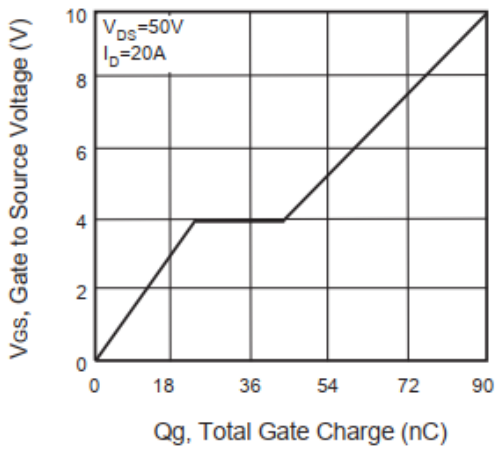


Figure 7. Gate Charge Characteristics

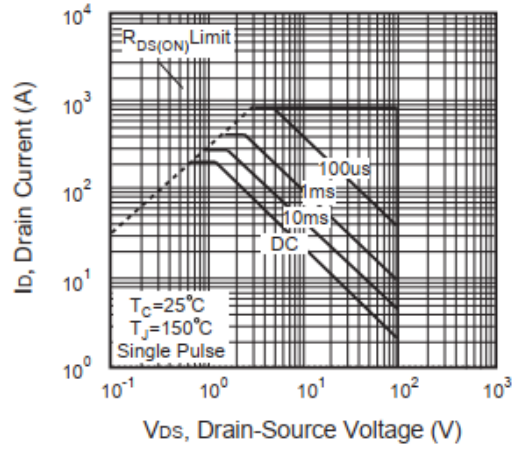


Figure 8. Maximum Safe Operating Area

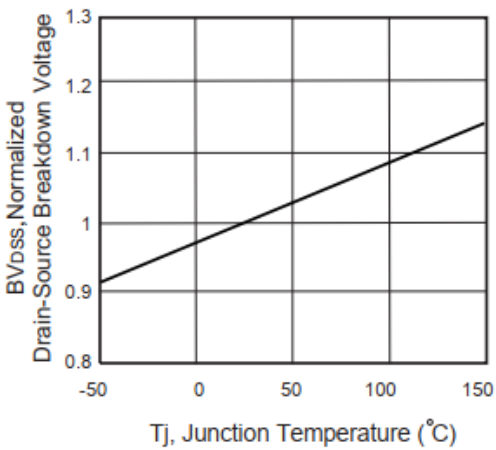


Figure 9. Breakdown Voltage Variation vs. Temperature

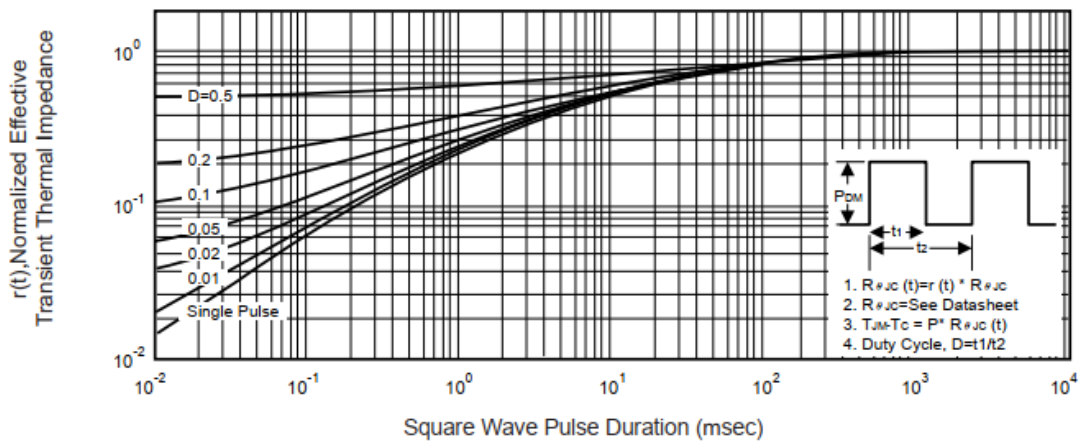
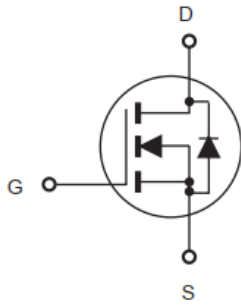


Figure 10. Normalized Thermal Transient Impedance Curve

- Circuit diagram



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